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1.SCOPE:

This specification covers the requirements for product performance of 1.00mm pitch board to

board connector series.

2.PART NAME & PART NUMBERS

Part name		Part number	
Wafer	Receptacle	B1000H B1000H-S B1000H-S-F	
	Header	B1000HM B1000HM-S B1000HM-S-F	

3. CONSTRUCTION. DIMENSIONS . MATERIAL & SURFACE FINISH

Construction and dimensions shall be in accordance with the referenced drawings. Material and surface finish shall be as specified below.

Part name		Material	Surface finish
Wafer	Post	Phosphor Bronze	Tin over Nickel/Gold over Nickel
	Body	Nylon 6T	UL94V-0

4. PERFORMANCE

4.1 ELECTRICAL PERFORMANCE

Test Description		Procedure	Requirement
5-1-1	Rating	Current rating & Voltage rating	0.5A AC DC 150V AC DC
5-1-3	Contact Resistance	Mate connectors, measure by dry circuit, 100mA. (Based upon JIS C5402 5.4)	$50 \mathrm{m}\Omega$ max.
5-1-4	Insulation Resistance	Mate connectors, apply 100V DC between adjacent terminal or ground. (Based upon JIS C5402 5.2/MIL-STD-202 Method 302 Cond. B)	500MΩ min.
5-1-5	Dielectric Withstanding Voltage	Mate connectors, apply 250V AC (rms) for 1 minute between adjacent terminal or ground. (Based upon JIS C5402 5.1/MIL-STD-202 Method 301)	No Breakdown

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4.2 MECHANICAL PERFORMANCE

Test Description		Procedure		Requirement
4-2-1	Durability	When mated up to 30 cycles repeatedly	Contact Resistance	$50 \mathrm{m}\Omega$ max.
4-2-2	Vibration	Amplitude: 0.75mm P-P Sweep time: 10-55-10 Hz in 1 minute Duration: 2 hours in each X.Y.Z. axes (Based upon MIL-STD-202 Method 201A)	Appearance	No Damage
			Contact Resistance	$50 \mathrm{m}\Omega$ max.
			Discontinuit y	lµsec. max.

4.3 ENVIRONMENTAL PERFORMANCE AND OTHERS

Test Description		Procedure		Requirement
	Heat Resistance	$105 \pm 2^{\circ}$ C, 96 hours	Appearance	No Damage
4-3-1		(Based upon JIS C0021/MIL-STD- 202 Method 108A Cond. A)	Contact Resistance	$50 \mathrm{m}\Omega$ max.
	Cold Resistance	-40 ± 3°C, 96 hours (Based upon JIS C0020)	Appearance	No Damage
4-3-2			Contact Resistance	$50m\Omega$ max.
	Humidity	Temperature: 40 ± 2°C Relative Humidity: 90 ~ 95% Duration: 96 hours (Based upon JIS C0022/MIL-STD- 202 Method 103B Cond. B)	Appearance	No Damage
4-3-3			Contact Resistance	$50 \mathrm{m}\Omega$ max.
			Insulation Resistance	500M Ω min.
4-3-4	Temperature Cycling	5 cycles of: a) - 40°C 30 minutes b) +105°C 30 minutes	Appearance	No Damage
			Contact Resistance	$50 \mathrm{m}\Omega$ max.
	Salt Spray	24 hours exposure to a salt spray from the $5 \pm 1\%$ solution at 35 ± 2 °C. (Based upon JIS C0023/MIL-STD-	Appearance	No Damage
4-3-5			Contact Resistance	$50 \mathrm{m}\Omega$ max.
4-3-6	Solderability	Soldering Time: 3 ± 0.5 sec. Solder Temperature: $245 \pm 5^{\circ}$ C	Solder Wetting	95% of immersed area must show
4-3-7	Resistance to Soldering Heat	Reflow soldering method (Up to 2 cycles)Soldering Time: 5 ± 0.5 sec.Solder Temperature: $250 \pm 5^{\circ}C$ Solder iron methodSoldering Time: 3 ± 0.5 sec.Solder Temperature: $380^{\circ}C$	Appearance	No Damage